

Preface

2014 2nd International Conference on Future Materials Engineering and Industry Application (ICFMEIA2014) will be held on December 10-11, 2014, Hong Kong. ICFMEIA 2014 provides a chance for academic and industry professionals to discuss recent progress in the area of Future Materials Engineering and Industry Application.

Materials engineering discussed the topical information on innovative, structural and functional materials and composites with applications in optical, electronical, mechanical, civil, aeronautical, medical, bio and nano engineering. Industrial engineering is a branch of engineering which deals with the optimization of complex processes or systems. It is concerned with the development, improvement, implementation of integrated systems of people, money, knowledge, information, equipment, energy, materials, analysis and synthesis, as well as the mathematical, physical and social sciences together with the principles and methods of engineering design to specify, predict, and evaluate the results to be obtained from such systems or processes.

ICFMEIA2014 is a very nice platform for sharing experiences, innovative ideas and research results focused on the progress of Future Materials Engineering and Industry Application. The aim of the conference is to assemble all the professionals such as leading researchers, engineers, scientists, and students under one roof.

We are thankful to colleagues for their contributions to ICFMEIA 2014. We also would like to thank the members of the Organizing Committee, IERI, and the corporate sponsors for their efforts and contributions towards making the conference successful. Special thanks go to TTP Publisher. Our sincerely acknowledgements are also expressed to the people who contribute to the proceedings and conference. Moreover, our thanks are also due to the sponsors for providing much help for the conference.

Finally, we hope the attendees benefit from the conference, and have a happy and meaningful journey in Hong Kong.

Thanks.

Barry Tan and Mont Kumpugdee Vollrath

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